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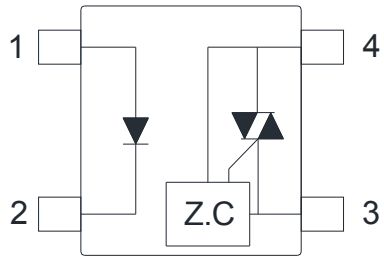
KTLP161L Series

4PIN MINI-FLAT ZERO-CROSS TRIAC DRIVER PHOTOCOUPLER

Description

The KTLP161L devices consist of a GaAs infrared emitting diode optically coupled to a monolithic silicon detector performing the function of a zero voltage crossing bilateral TRIAC driver. They are designed for use with a TRIAC in the interface of logic systems to equipment powered from 240 VAC lines, such as solid-state relays, industrial controls, motors, solenoids and consumer appliances, etc.

Schematic



1. Anode
2. Cathode
3. Main terminal
4. Main terminal

Features

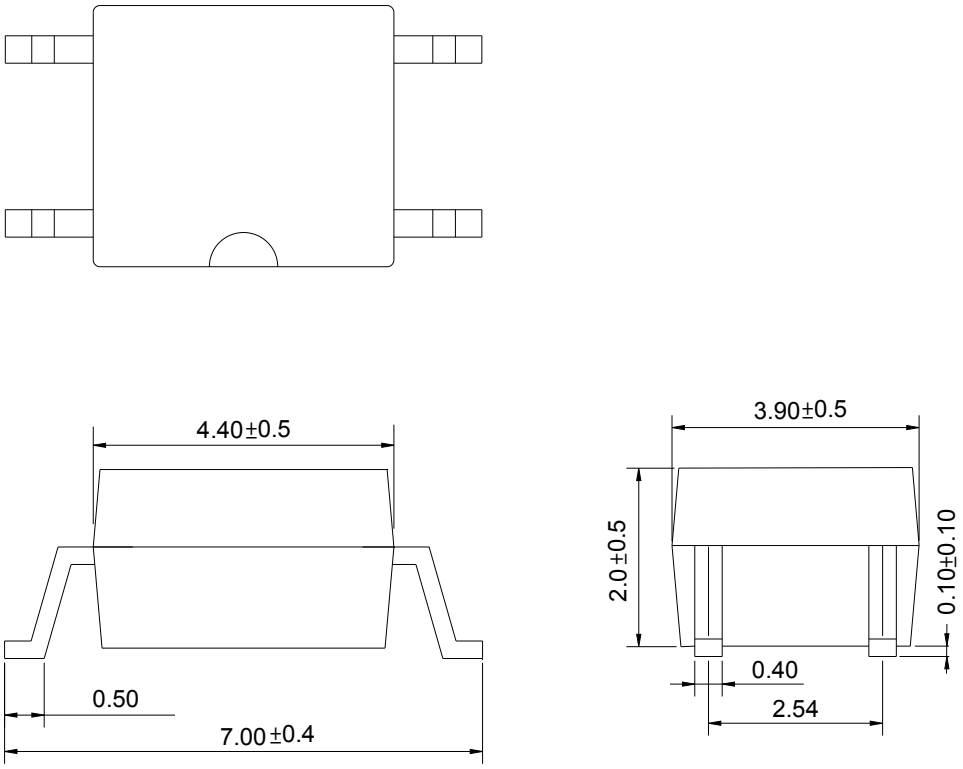
1. Pb free and RoHS compliant
2. 800V peak blocking voltage
3. Subminiature type (The volume is smaller than that of our conventional DIP type by as far as 30%)
4. Simplifies logic control of 240 VAC power
5. Zero voltage crossing
6. Isolation voltage between input and output (Viso：3750Vms)
7. Agency Approvals：
   - UL1577, File No. E169586
   - CUL C22.2 No.1 & NTC No.5, File No. E169586
   - VDE EN60747-5-2 , File No. 40020973

Applications

- Solenoid/Valve controls
- Lighting controls
- Static power switches
- AC motor drives
- Temperature controls
- E.M contactors
- AC motor contactors
- Solid state relay
- Programmable controllers

● Outside Dimension

Unit：mm



TOLERANCE : ±0.2mm

● Device Marking

Notes :

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161L
YWW　Y：Year code / W：Week code

● Absolute Maximum Ratings

(Ta=25℃)

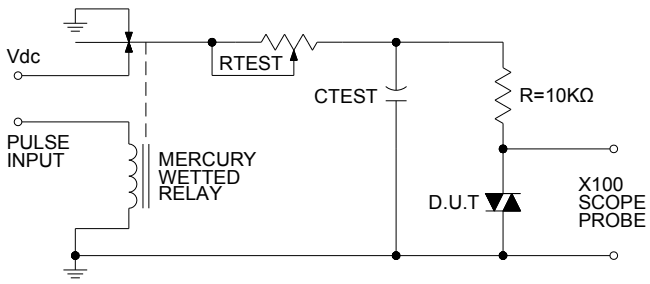
Parameter		Symbol	Rating	Unit
Input	Forward current	I_F	50	mA
	Peak forward current	I_{FM}	1	A
	Reverse voltage	V_R	6	V
	Power dissipation	P_D	70	mW
Output	Off-state output terminal voltage	V_{DRM}	800	V_{PEAK}
	On-state R.M.S. current	$I_{T(RMS)}$	70	mA
	Peak repetitive surge current (PW=10ms.DC 10%)	I_{TSM}	1	A
	Power dissipation	P_D	150	mW
Total power dissipation		P_{tot}	200	mW
Isolation voltage 1 minute		V_{iso}	3750	Vrms
Operating temperature		T_{opr}	-40 to +115	℃
Storage temperature		T_{stg}	-50 to +125	℃
Soldering temperature 10 seconds		T_{sol}	260	℃

● Electro-optical Characteristics

(Ta=25℃)

Parameter		Symbol	Conditions	Min.	Typ.	Max.	Unit
Input	Forward voltage	V_F	I_F=10mA	-	1.2	1.4	V
	Reverse current	I_R	V_R=4V	-	-	10	μA
Output	Peak blocking current	I_{DRM}	V_{DRM} Rated	-	-	1	μA
	On-state voltage	V_{TM}	I_{TM}=70mA	-	1.8	3	V
Transfer charac-teristics	Holding current	I_H		-	0.1	-	mA
	Critical rate of rise of off-state voltage	dv/dt	V_{DRM}=(1/$\sqrt{2}$)*Rated	1000	-	-	V/μs
	Inhibit voltage (MT1-MT2 voltage above which device will not trigger)	V_{INH}	I_F= Rated I_{FT}	-	10	20	V
	Leakage in inhibited state	I_{DRM2}	I_F=Rated I_{FT}, Rated V_{DRM}, Off-state	-	500-	1000	μA
	Isolation resistance	R_{iso}	DC500V	$5x10^{10}$	10^{11}	-	Ω
	Minimum trigger current	I_{FT}	Main terminal voltage=3V	-	-	10	mA

● Static dv/dt Test Circuit



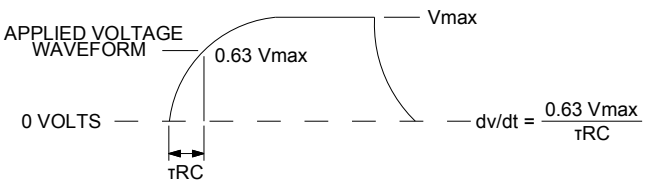


Fig.1 Forward Current vs. Ambient Temperature

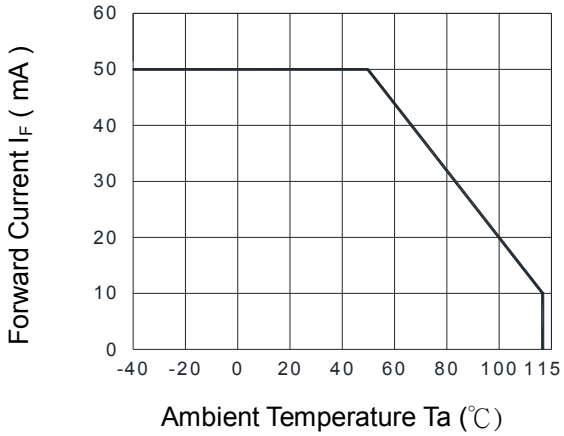


Fig.2 Diode Power Dissipation vs. Ambient Temperature

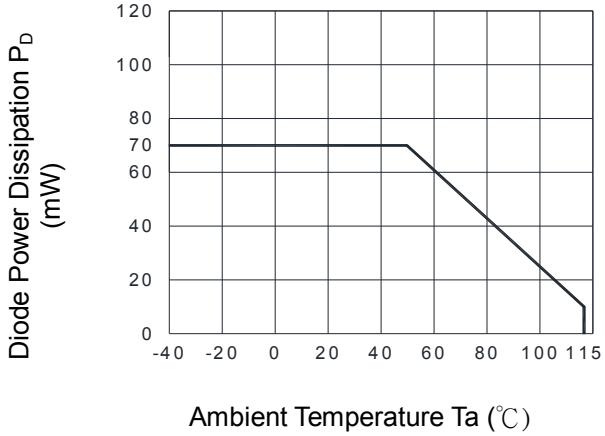


Fig.3 On-state R.M.S. Current vs. Ambient Temperature

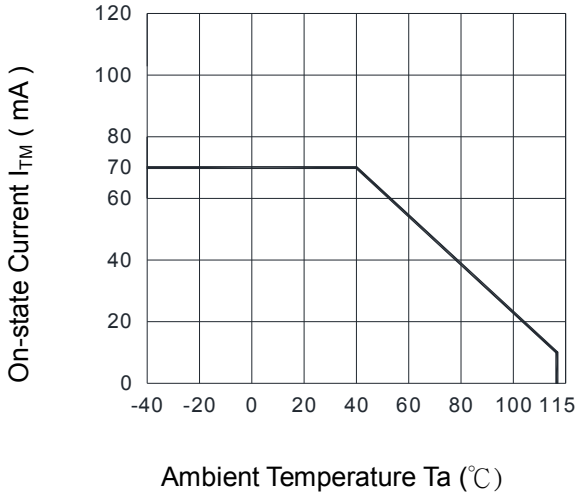


Fig.4 Total Power Dissipation vs. Ambient Temperature

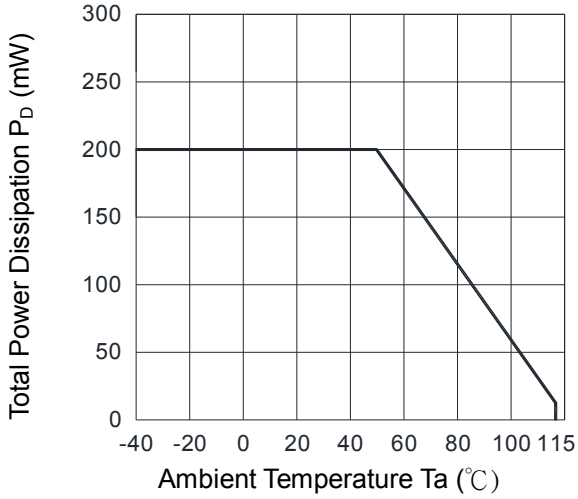


Fig.5 Peak Forward Current vs. Duty Ratio

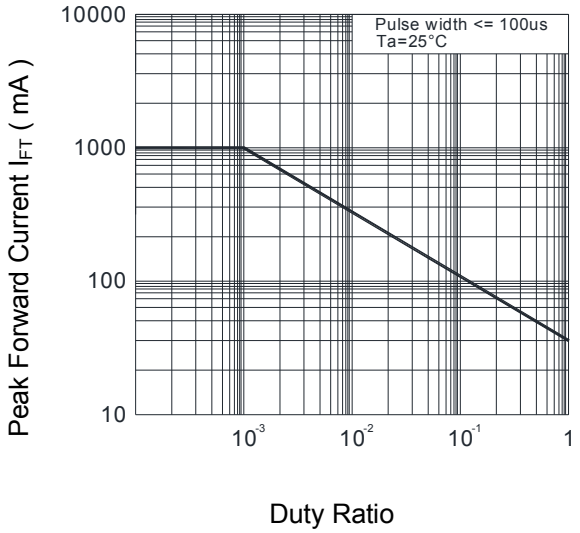


Fig.6 Forward Current vs. Forward Voltage

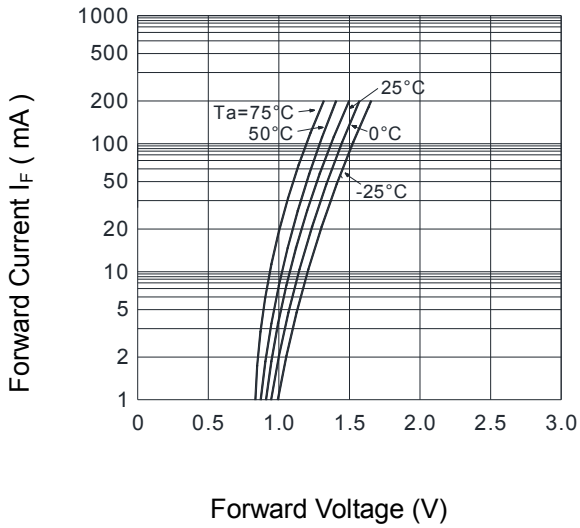


Fig.7 On-state Characteristics

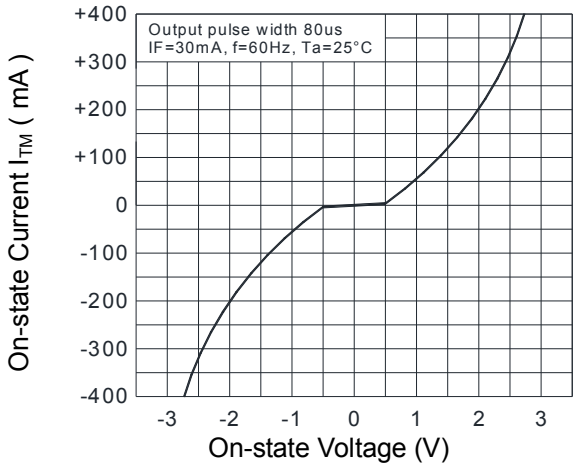


Fig.8 Inhibit Voltage vs. Ambient Temperature

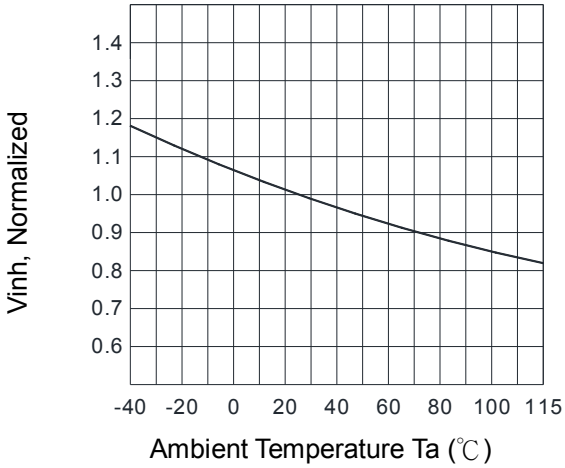


Fig.9 Leakage with LED off vs. Ambient Temperature

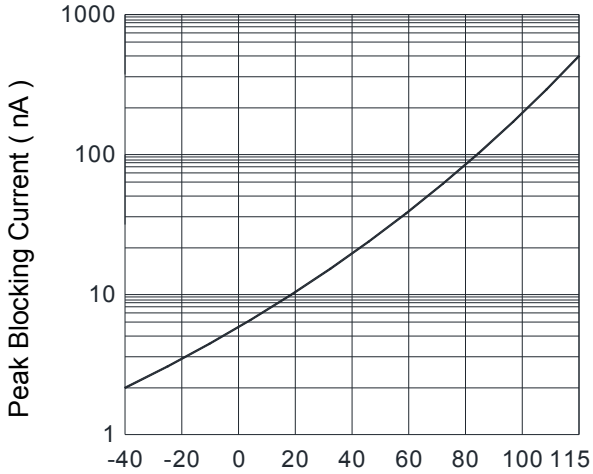


Fig.10 I_{DRM2} ,Leakage in Inhibited State vs. Ambient Temperature

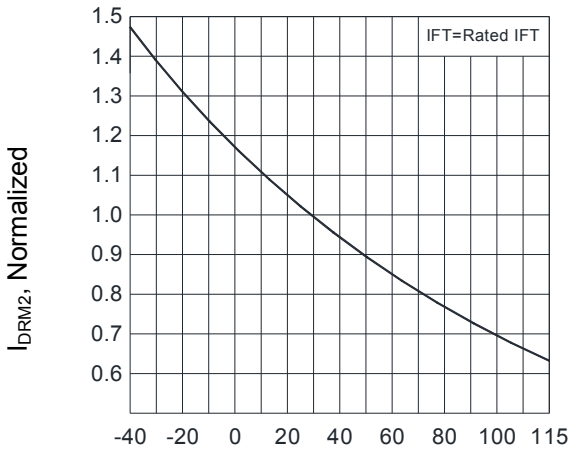
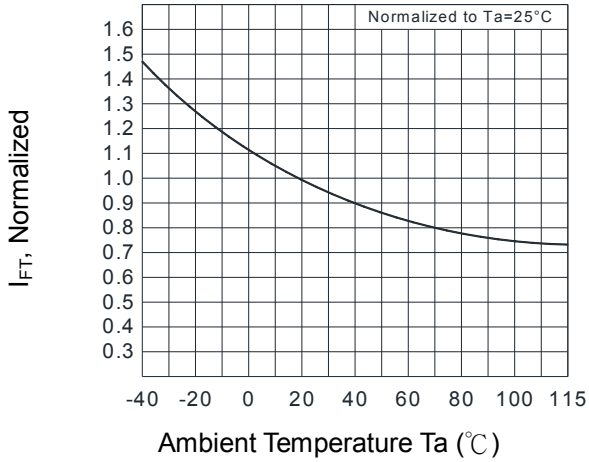


Fig.11 Trigger Current vs. Ambient Temperature

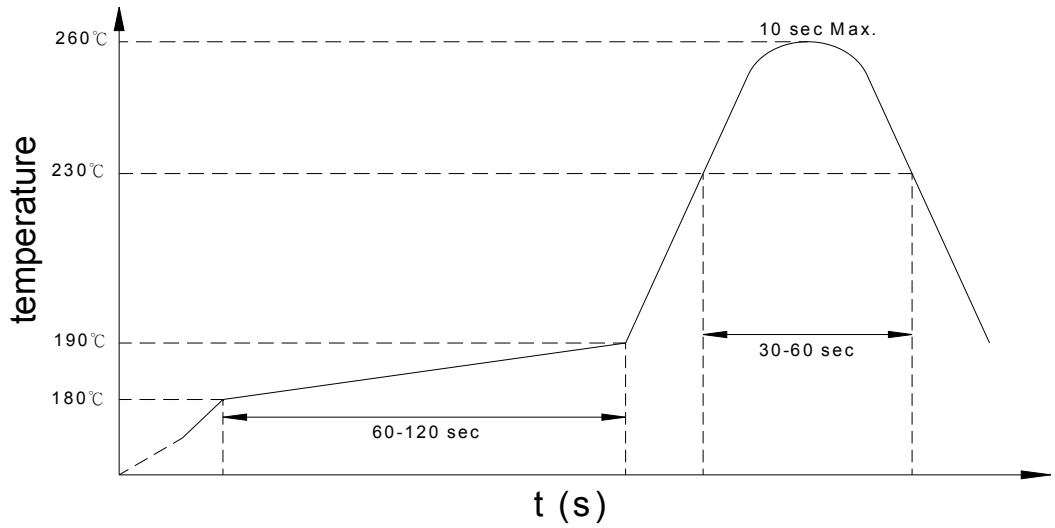


Recommended Soldering Conditions

(a) Infrared reflow soldering :

- Peak reflow soldering : 260℃ or below (package surface temperature)
- Time of peak reflow temperature : 10 sec
- Time of temperature higher than 230℃ : 30-60 sec
- Time to preheat temperature from 180~190℃ : 60-120 sec
- Time(s) of reflow : Two
- Flux : Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(b) Wave soldering :

- Temperature : 260℃ or below (molten solder temperature)
- Time : 10 seconds or less
- Preheating conditions : 120℃ or below (package surface temperature)
- Time(s) of reflow : One
- Flux : Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(c) Cautions :

- Fluxes : Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.
- Avoid shorting between portion of frame and leads.

● Numbering System

KTLP161L (X)

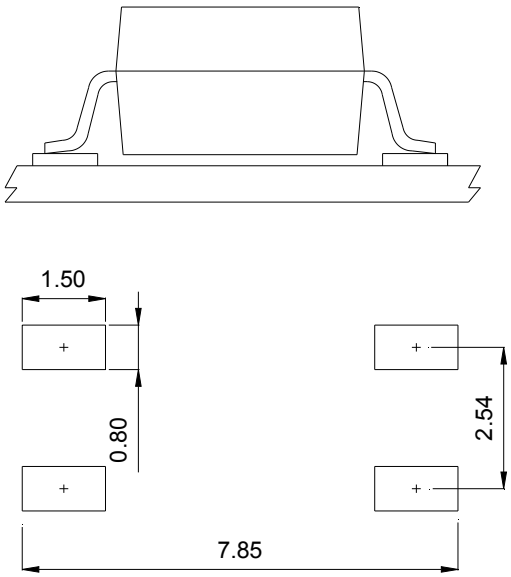
Notes：

KTLP161L = Part No.

X = Tape and reel option (TLD、TRU)

Option	Description	Packing quantity
TLD	surface mount type package + TLD tape & reel option	3000 units per reel
TRU	surface mount type package + TRU tape & reel option	3000 units per reel

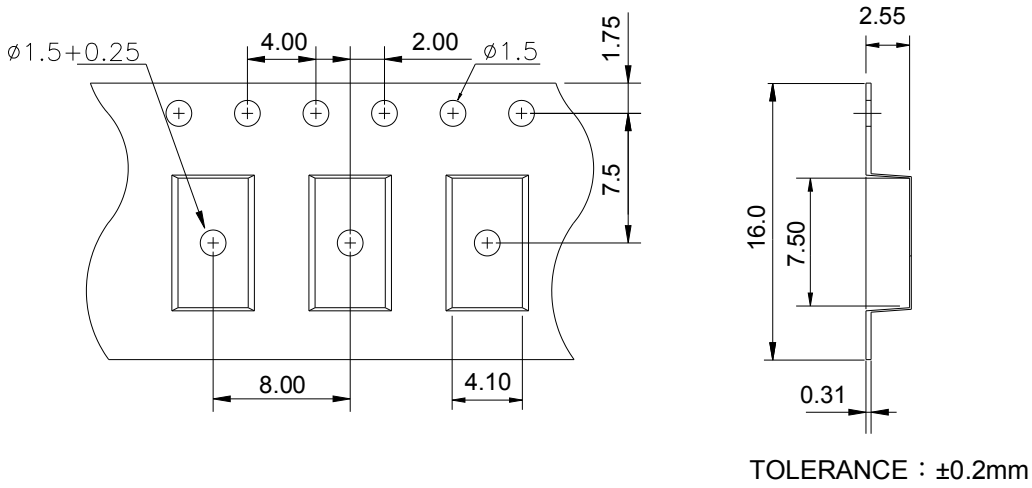
● Recommended Pad Layout for Surface Mount Lead Form



Unit：mm

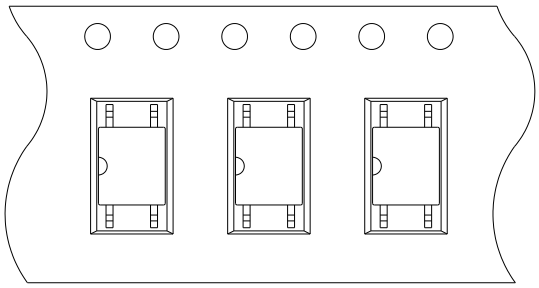
● 4-pin Mini-Flat TLD/TRU Carrier Tape & Reel

Unit：mm

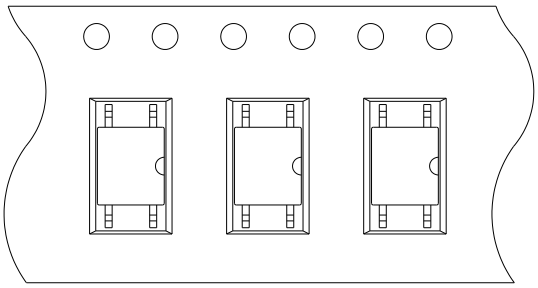


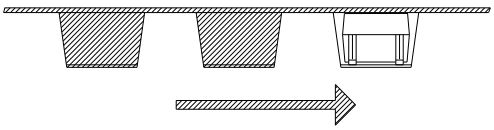
TOLERANCE：±0.2mm

TLD

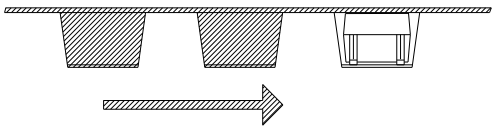


TRU

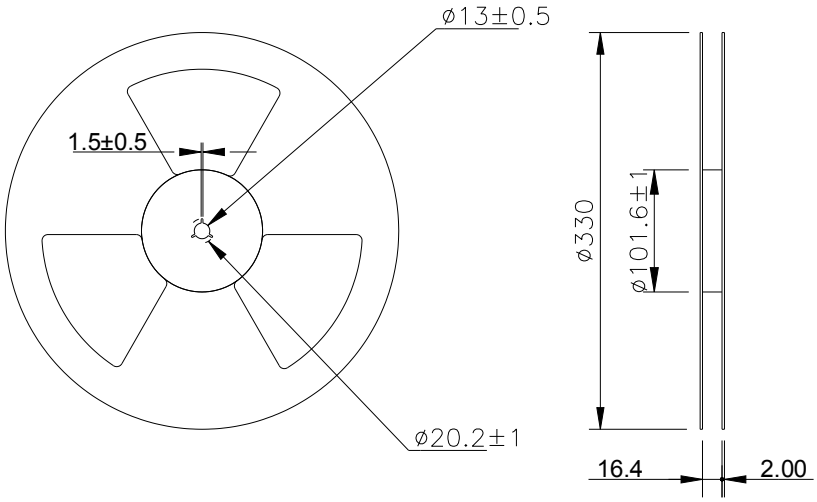




Direction of feed from reel



Direction of feed from reel



Application Notice

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cosmo products are intended to be designed for use in general electronics application list below:

a. Personal computer
b. OA machine
c. Audio / Video
d. Instrumentation
e. Electrical application
f. Measurement equipment
g. Consumer electronics
h. Telecommunication

cosmo devices shall not be used or related with equipment requiring higher level of quality / reliability, or malfunction, or failure which may cause loss of human life, bodily injury, includes, without limitation:

a. Medical and other life supporting equipments
b. Space application
c. Telecommunication equipment (trunk lines)
d. Nuclear power control
e. Equipment used for automotive vehicles, trains, ships...etc.